

Title of Change:	Transfer of Assembly and Test operation of DPAK package (Case outline 369C) from onsemi Seremban, Malaysia to JCET Semiconductor (Suqian) Co.Ltd., China		
Proposed Changed Material First Ship Date:	01 Oct 2023 or earlier if approved by customer		
Current Material Last Order Date:	30 Apr 2023 Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.		
Current Material Last Delivery Date:	30 Sep 2023 The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory		
Product Category:	Active components – Integrated circuits		
Contact information:	Contact your local onsemi Sales Office or Juraj.Kremmer@onsemi.com		
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Additional Reliability Data:	Contact your local onsemi Sales Office or MohdAzizi.Azman@onsemi.com		
This is an Initial Product/Process Change Notification (IPCN) sent to customers. An I advance notification about an upcoming change and contains general information r the change details and devices affected. It also contains the preliminary reliability q plan. The completed qualification and characterization data will be included in the F Product/Process Change Notification (FPCN). This IPCN notification will be followed Product/Process Change Notification (FPCN) at least 6 months prior to implementar change. In case of questions, contact < PCN.Support@onsemi.com >.			
Change Category			
Category	Type of Change		
Test Flow	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor		
Equipment	Production from a new equipment/tool which uses the same basic technology (replacement equipment or extension of existing equipment pool) without change of process.		
Process - Assembly	Move of all or part of assembly to a different location/site/subcontractor., Change of mold compound, Die attach material, Change of lead frame finishing material / area (internal), Change of product marking		

Description and Purpose:

This Initial Notification announces to customers of onsemi's plans to Transfer Assembly and Test operations of the DPAK package (Case Outline 369C) products from onsemi Seremban, Malaysia to JCET Semiconductor (Suqian) Co.Ltd., China.



			l	From		То	
As:	sembly / Test Site		onsemi, Sere	emban, Malaysia	JCET Semiconductor Co.Ltd., Suqian, Ch		
	LeadFrame		No	plating	Ag plating		
	Die Attach		Pb	95Sn5	Pb95.5Sn2Ag2.5		
Ν	Mold Compound		G	700HF	CEL-9240HF(Green)		
	•		GE 80	GE 8000CH4ES		. ,	
Reason / Motiv	vation for Change:	Source/S	Supply/Capacity Chan	ges Process/Materials Cha	nge		
Anticipated im function, reliat safety or manu	pact on fit, form, pility, product ıfacturability:	The device will be qualified an No anticipated impacts.		nd validated based on the s	same Product Specification		
Sites Affected:							
onsemi Sites				External Foundry/Sub	ocon Sites		
onsemi Seremba	n, Malaysia			JCET, China			
Marking of Parts/ Traceability of Changed material can be identified by assembly plant code. Change:							
QV DEVICE NAI RMS : 84637 PACKAGE : DP4	ME : NCV4274ADT50 AK	RKG-IRO	1				
Test	Specifica	tion		Condition		Interval	
HTOL	JESD22-A	108		Ta=125°C, 100 % max	rated Vcc	1008 hrs	
ELFR	JESD22-A	108		Ta=125°C, 100 % max	rated Vcc	48 hrs	
HTSL	JESD22-A103		Ta= 150°C		2016 hrs		
LTSL	JESD22-A119		Ta= -40°C		168 hrs		
PC	J-STD-020 JESD-A113		MSL 1 @ 260°	°C			
TC	JESD22-A104		Ta= -65°C to +150°C, mo	unt on board	500 cyc		
РТС	JESD22-A105		Ta= -40°C to +125°C, mo	unt on board	1000 сус		
HAST	JESD22-A110		130°C, 85% RH, 18.8	psig, bias	192 hrs		
uHAST	JESD22-A118		130°C, 85% RH, 18.8psi	g, unbiased	96 hrs		
RSH	JESD22- B106		Ta = 265°C, 10 s	sec e devices only			
				Required for through hole			

onsemi

Initial Product/Process Change Notification Document #:IPCN24896Z Issue Date:29 Sep 2022

QV DEVICE NAME : NCV4274CDT50RKG RMS : 84639 PACKAGE : DPAK

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
ELFR	JESD22-A108	Ta=125°C, 100 % max rated Vcc	48 hrs
HTSL	JESD22-A103	Ta= 150°C	2016 hrs
LTSL	JESD22-A119	Ta= -40°C	168 hrs
РС	J-STD-020 JESD-A113	MSL 1 @ 260°C	
ТС	JESD22-A104	Ta= -65°C to +150°C, mount on board	500 cyc
PTC	JESD22-A105	Ta= -40°C to +125°C, mount on board	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
RSH	JESD22- B106	Ta = 265°C, 10 sec Required for through hole devices only	
SD	JSTD002	Ta = 245°C, 5 sec	

QV DEVICE NAME : NCV8774CDT50RKG RMS : 84638 PACKAGE : DPAK

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
ELFR	JESD22-A108	Ta=125°C, 100 % max rated Vcc	48 hrs
HTSL	JESD22-A103	Ta= 150°C	2016 hrs
LTSL	JESD22-A119	Ta= -40°C	168 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C	
тс	JESD22-A104	Ta= -65°C to +150°C, mount on board	500 сус
РТС	JESD22-A105	Ta= -40°C to +125°C, mount on board	1000 сус
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
RSH	JESD22- B106	Ta = 265°C, 10 sec Required for through hole devices only	
SD	JSTD002	Ta = 245°C, 5 sec	

onsemi

QV DEVICE NAME : NCV1117DT50RKG RMS : 84204 PACKAGE : DPAK

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
ELFR	JESD22-A108	Ta=125°C, 100 % max rated Vcc	48 hrs
HTSL	JESD22-A103	Ta= 150°C	2016 hrs
LTSL	JESD22-A119	Ta= -40°C	168 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C	
TC	JESD22-A104	Ta= -65°C to +150°C, mount on board	500 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
RSH	JESD22- B106	Ta = 265°C, 10 sec Required for through hole devices only	
SD	JSTD002	Ta = 245°C, 5 sec	

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

Current Part Number	New Part Number	Qualification Vehicle
NCV4274ADT50RKG	NA	NCV4274ADT50RKG-IR01
NCV4274ADT50RKG-IR01	NA	NCV4274ADT50RKG-IR01
NCV8664DT50RKG	NA	NCV4274ADT50RKG-IR01
NCV4274CDT33RKG	NA	NCV4274CDT50RKG
NCV4274CDT50RKG	NA	NCV4274CDT50RKG
NCV8664CDT33RKG	NA	NCV4274CDT50RKG
NCV8664CDT50RKG	NA	NCV4274CDT50RKG
NCV8774CDT33RKG	NA	NCV8774CDT50RKG
NCV8774CDT50RKG	NA	NCV8774CDT50RKG
NCV1117DT12RKG	NA	NCV1117DT50RKG
SA317MDTRKG	NA	NCV1117DT50RKG
SA317MBDTRKG	NA	NCV1117DT50RKG
NCV7808BDTRKG	NA	NCV1117DT50RKG



Initial Product/Process Change Notification Document #:IPCN24896Z Issue Date:29 Sep 2022

NCV7805BDTRKG-IR01	NA	NCV1117DT50RKG
NCV7805BDTRKG	NA	NCV1117DT50RKG
NCV317MBDTRKG	NA	NCV1117DT50RKG
NCV317MABDTRKG	NA	NCV1117DT50RKG
NCV78M12BDTRKG	NA	NCV1117DT50RKG
NCV78M08BDTRKG	NA	NCV1117DT50RKG
NCV78M05BDTRKG	NA	NCV1117DT50RKG
NCV78M05ABDTRKG	NA	NCV1117DT50RKG
NCV33269DTRKG	NA	NCV1117DT50RKG
NCV33269DTRK5.0G	NA	NCV1117DT50RKG
NCV33269DTRK3.3G	NA	NCV1117DT50RKG
NCV5501DT50RKG	NA	NCV1117DT50RKG
NCV5501DT33RKG	NA	NCV1117DT50RKG
NCV5501DT15RKG	NA	NCV1117DT50RKG
NCV2931ADT5.0RKG	NA	NCV1117DT50RKG
NCV1117DTARKG	NA	NCV1117DT50RKG
NCV1117DT50RKG	NA	NCV1117DT50RKG
NCV1117DT33T5G	NA	NCV1117DT50RKG
NCV1117DT18T5G	NA	NCV1117DT50RKG
NCV1117DT18RKG	NA	NCV1117DT50RKG
NCV1117DT15RKG	NA	NCV1117DT50RKG